

AMENDMENTS TO THE CLAIMS

Claims 1-8 (canceled).

9. (Currently Amended) A method for decapsulating installed integrated circuit (IC) packages, comprising:

receiving an IC package, ~~installed~~bonded onto a printed circuit board via a surface mount attachment;
placing the installed IC package onto a tray;
clamping an injection head onto the installed IC package; and,
spraying decapsulation fluid onto the installed IC package through the injection head.

10. (Previously Presented) The method as recited in claim 9, further comprising:
moving a stub that is plugged into the tray and which supports the printed circuit board of the installed IC package before the installed IC package is placed onto said tray.

11. (Previously Presented) The method as recited in claim 9, further comprising:
controlling a flow of the decapsulation fluid through a pair of tubes that couple an extender to the injection head using a corresponding pair of valves.

12. (Previously Presented) The method as recited in claim 9, further comprising:
plugging a stub that supports the printed circuit board of the installed IC package into a substrate of the tray.

13. (Currently Amended) A method for decapsulating installed integrated circuit (IC) packages, comprising:

receiving an IC package ~~installed~~bonded onto a first surface of a printed circuit board (PCB) via a surface mount attachment wherein the printed circuit board includes a second surface located below the first surface of the printed circuit board;

spraying a decapsulation fluid onto the installed IC package via an injection head clamped to the installed IC package, the injection head having a nozzle disposed above the installed IC package that is in fluid communication with an inlet port of said injection head, and a return port that is in fluid communication with an outlet port of the injection head.

14. (Previously Presented) The method as recited in claim 13, further comprising:
controlling a flow of the decapsulation fluid through a pair of tubes that couple an
extender to the injection head using a corresponding pair of valves.

15. (Previously Presented) The method as recited in claim 13, further comprising:
plugging a stub that supports the PCB of the installed IC package into a substrate.

16. (Previously Presented) The method as recited in Claim 13 further comprising:
forming a seal between injection head and the installed IC package to prevent
decapsulation fluid from contacting the PCB of the installed IC package.